

General Description

This IGBT is produced using advanced MagnaChip's Field Stop Trench IGBT Technology, which provides high performance, excellent quality and high ruggedness.

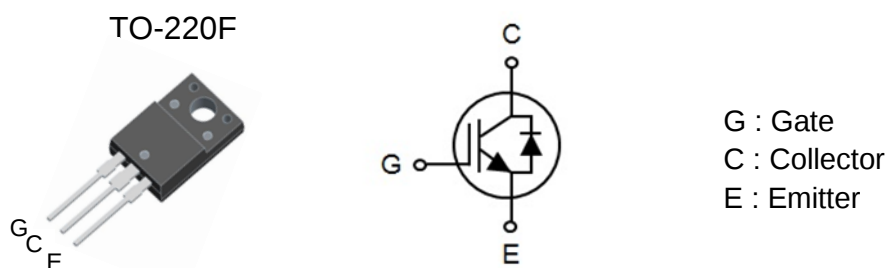
This device is for motor control.

Features

- High ruggedness for motor control
- $V_{CE(sat)}$ positive temperature coefficient
- Very soft, fast recovery anti-parallel diode
- Low EMI
- Maximum junction temperature 175°C

Applications

- Inverter for motor control



Package outline and symbol

Maximum Ratings

Parameter		Symbol	Rating	Unit
Collector-emitter voltage		V _{CE}	650	V
DC collector current, limited by T _{vjmax}	T _C =25°C	I _C	30	A
	T _C =100°C		15	A
Pulsed collector current, t _p limited by T _{vjmax}		I _{Cpuls}	60	A
Diode forward current, limited by T _{vjmax}	T _C =25°C	I _F	30	A
	T _C =100°C		15	
Diode pulsed current, t _p limited by T _{vjmax}		I _{Fpuls}	60	A
Gate-emitter voltage		V _{GE}	±20	V
Power dissipation	T _C =25°C	P _D	48	W
	T _C =100°C		24	W
Short circuit withstand time V _{CC} ≤ 360V, V _{GE} = 15V, T _{vj} = 150°C		t _{sc}	5	μs
Operating Junction temperature range		T _{vj}	-40~175	°C
Storage temperature range		T _{sta}	-55~150	°C

Thermal Characteristics

Parameter	Symbol	Rating	Unit
Thermal resistance junction-to-ambient	$R_{th(j-a)}$	62	$^{\circ}C/W$
Thermal resistance junction-to-case for IGBT	$R_{th(j-c)}$	3.0	
Thermal resistance junction-to-case for Diode	$R_{th(j-c)}$	5.0	

Ordering Information

Part Number	Marking	Temp. Range	Package	Packing	RoHS Status
MBF15T65PEH	15T65PEH	-55~150°C	TO-220F	Tube	Halogen Free

Electrical Characteristics ($T_{vj} = 25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions		Min	Typ	Max	Unit
Static Characteristics							
Collector-emitter breakdown voltage	BV_{CES}	$I_C = 2\text{mA}$, $V_{GE} = 0\text{V}$		650	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 15\text{A}$, $V_{GE} = 15\text{V}$	$T_{vj} = 25^{\circ}\text{C}$		1.65	2.00	V
			$T_{vj} = 175^{\circ}\text{C}$		1.90		
Diode forward voltage	V_F	$V_{GE} = 0\text{V}$, $I_F = 15\text{A}$	$T_{vj} = 25^{\circ}\text{C}$		1.85	2.30	V
			$T_{vj} = 175^{\circ}\text{C}$		1.95		
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$, $I_C = 0.5\text{mA}$		4.5	5.5	6.5	V
Zero gate voltage collector current	I_{CES}	$V_{CE} = 650\text{V}$, $V_{GE} = 0\text{V}$, $T_{vj} = 25^{\circ}\text{C}$		-	-	20	μA
Gate-emitter leakage current	I_{GES}	$V_{GE} = 20\text{V}$, $V_{CE} = 0\text{V}$		-	-	± 100	nA
Dynamic Characteristics							
Total gate charge	Q_G	$V_{CE} = 520\text{V}$, $I_C = 15\text{A}$, $V_{GE} = 15\text{V}$		-	61		nC
Gate-emitter charge	Q_{GE}			-	11		
Gate-collector charge	Q_{GC}			-	35		
Input capacitance	C_{ies}	$V_{CE} = 25\text{V}$, $V_{GE} = 0\text{V}$, $f = 1\text{MHz}$		-	1129	-	pF
Output capacitance	C_{oes}			-	57	-	
Reverse transfer capacitance	C_{res}			-	31	-	
Switching Characteristics							
Turn-on delay time	$t_{d(on)}$	$V_{GE} = 15\text{V}$, $V_{CC} = 400\text{V}$, $I_C = 15\text{A}$, $R_G = 10\Omega$, Inductive Load, $T_{vj} = 25^{\circ}\text{C}$		-	19	-	ns
Rise time	t_r			-	27	-	
Turn-off delay time	$t_{d(off)}$			-	128	-	
Fall time	t_f			-	32	-	
Turn-on switching energy	E_{on}			-	270	-	μJ
Turn-off switching energy	E_{off}			-	86	-	
Total switching energy	E_{ts}			-	356	-	
Turn-on delay time	$t_{d(on)}$	$V_{GE} = 15\text{V}$, $V_{CC} = 400\text{V}$, $I_C = 15\text{A}$, $R_G = 10\Omega$, Inductive Load, $T_{vj} = 175^{\circ}\text{C}$		-	17	-	ns
Rise time	t_r			-	29	-	
Turn-off delay time	$t_{d(off)}$			-	150	-	
Fall time	t_f			-	130	-	
Turn-on switching energy	E_{on}			-	342	-	μJ
Turn-off switching energy	E_{off}			-	288	-	
Total switching energy	E_{ts}			-	630	-	
Reverse recovery time	t_{rr}	$I_F = 15\text{A}$, $di_F/dt = 200\text{A}/\mu\text{s}$, $T_{vj} = 25^{\circ}\text{C}$		-	150	-	ns
Reverse recovery current	I_{rr}			-	5.2	-	A
Reverse recovery charge	Q_{rr}			-	390	-	nC
Reverse recovery time	t_{rr}	$I_F = 15\text{A}$, $di_F/dt = 200\text{A}/\mu\text{s}$, $T_{vj} = 175^{\circ}\text{C}$		-	207	-	ns
Reverse recovery current	I_{rr}			-	6.1	-	A
Reverse recovery charge	Q_{rr}			-	631	-	nC

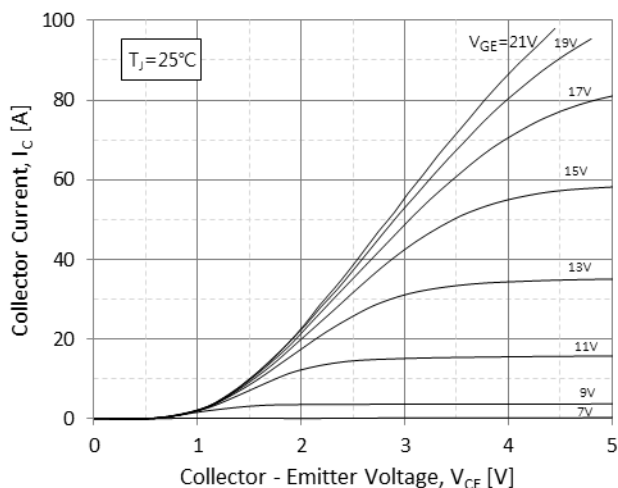


Fig.1 Typical Output Characteristics($T_J=25^\circ\text{C}$)

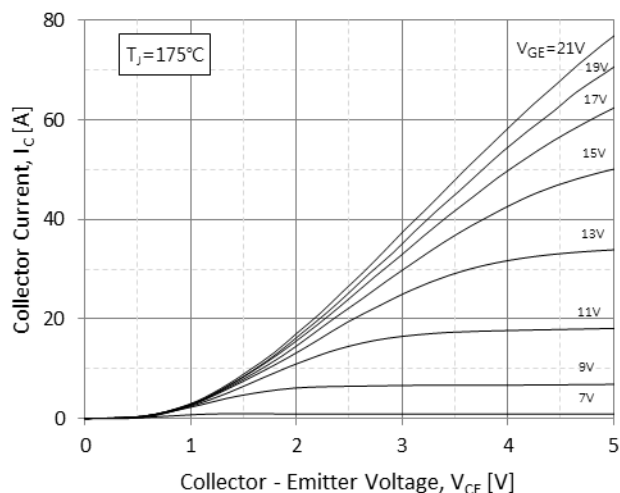


Fig.2 Typical Output Characteristics($T_J=175^\circ\text{C}$)

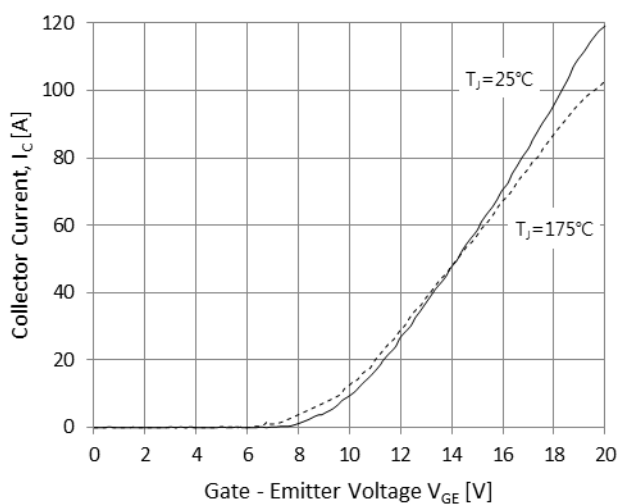


Fig.3 Typical Transfer Characteristics

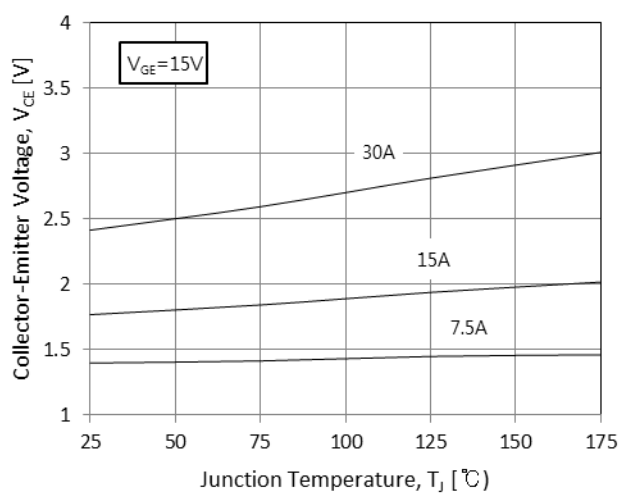


Fig.4 Typical Collector-Emitter Saturation Voltage -Junction Temperature

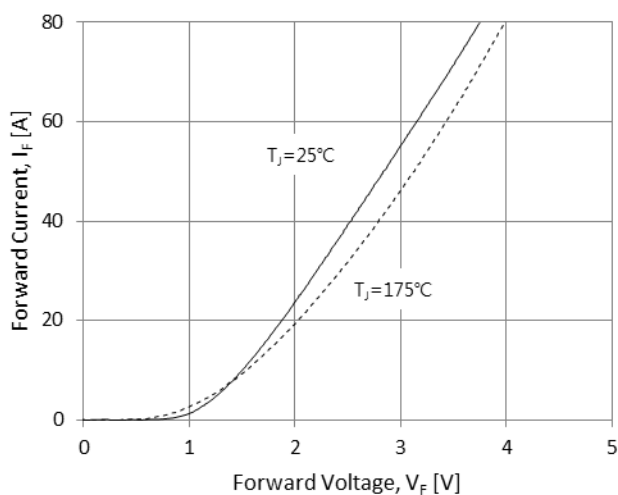


Fig.5 Diode Forward Characteristics

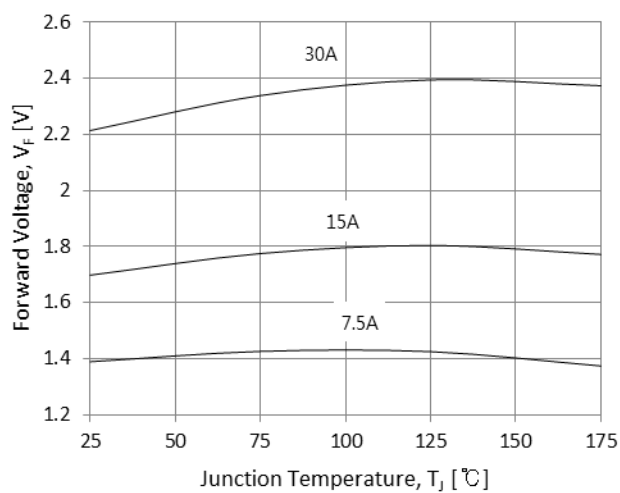


Fig.6 Diode Forward-Junction Temperature

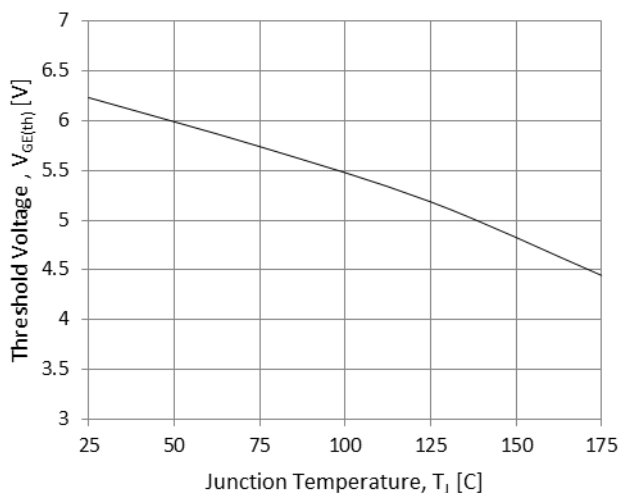


Fig.7 Threshold Voltage-Junction Temperature

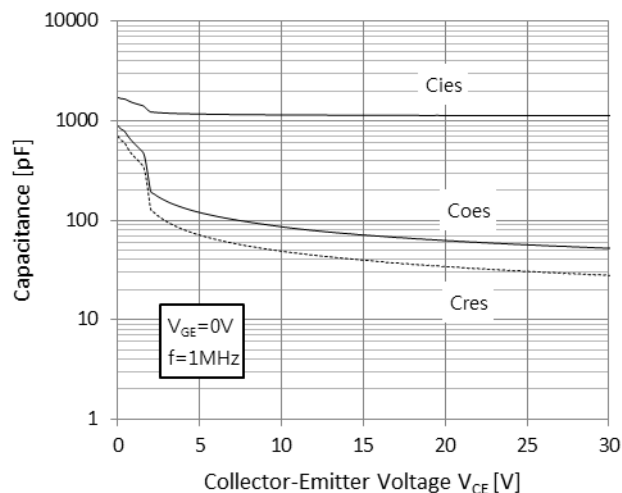


Fig.8 Typical Capacitance

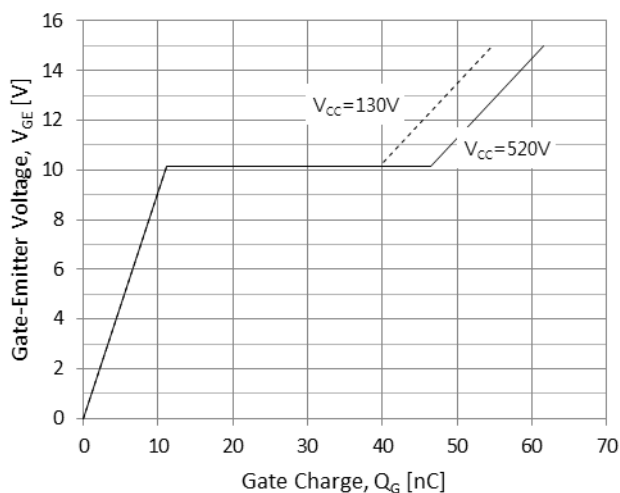


Fig.9 Typical Gate Charge

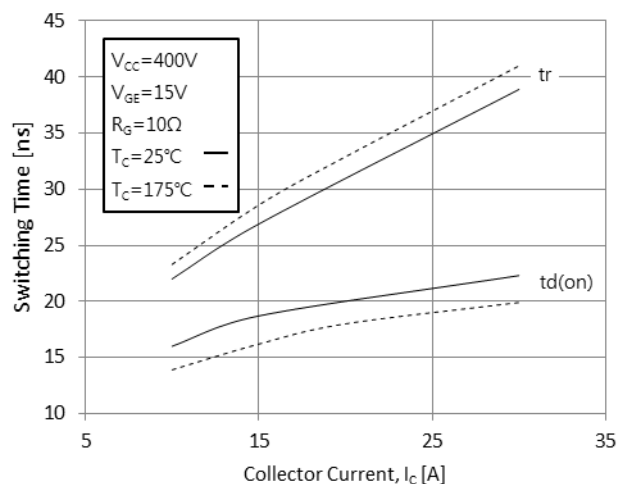


Fig.10 Typical Turn on-Collector Current

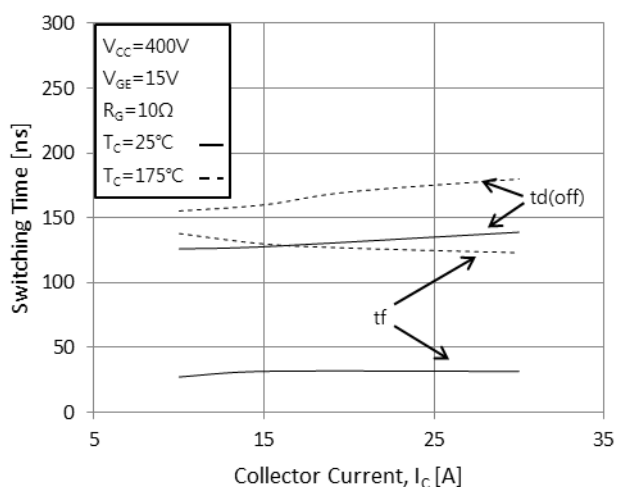


Fig.11 Typical Turn off-Collector Current

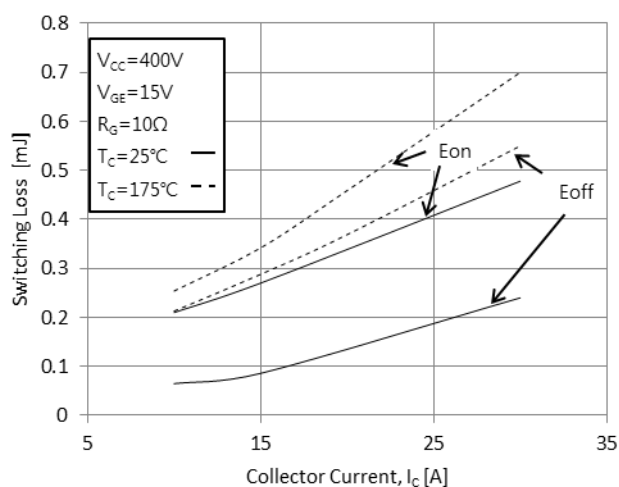


Fig.12 Switching Loss-Collector Current

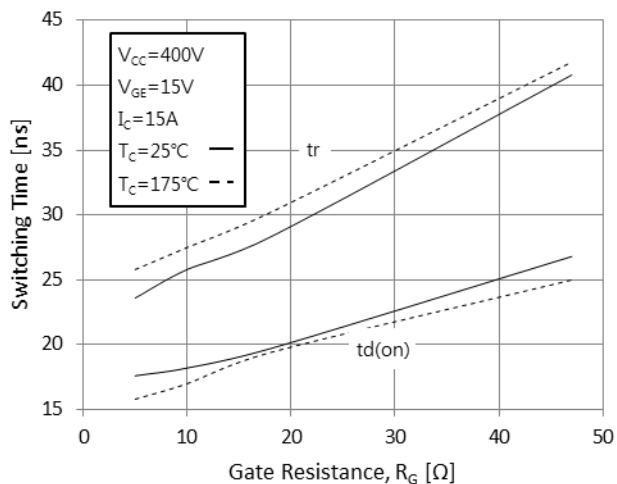


Fig.13 Turn on Characteristics-Gate Resistance

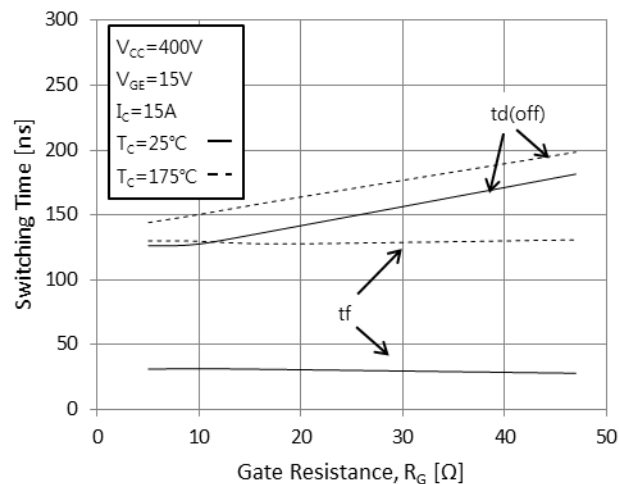


Fig.14 Turn off Characteristics-Gate Resistance

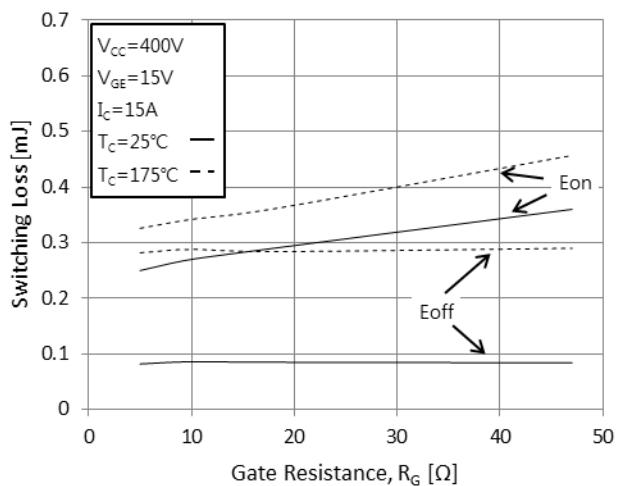


Fig.15 Switching Loss-Gate Resistance

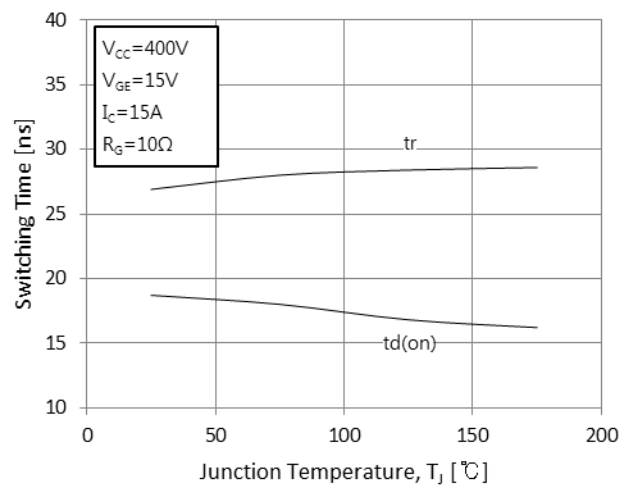


Fig.16 Turn on Characteristics-Junction Temperature

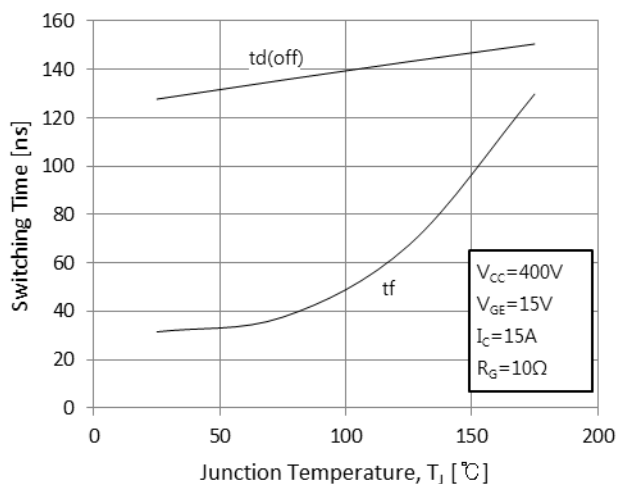


Fig.17 Turn off Characteristics-Junction Temperature

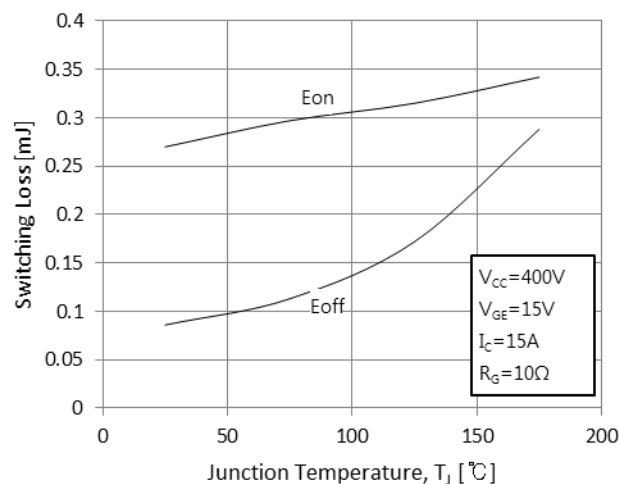


Fig.18 Switching Loss-Junction Temperature

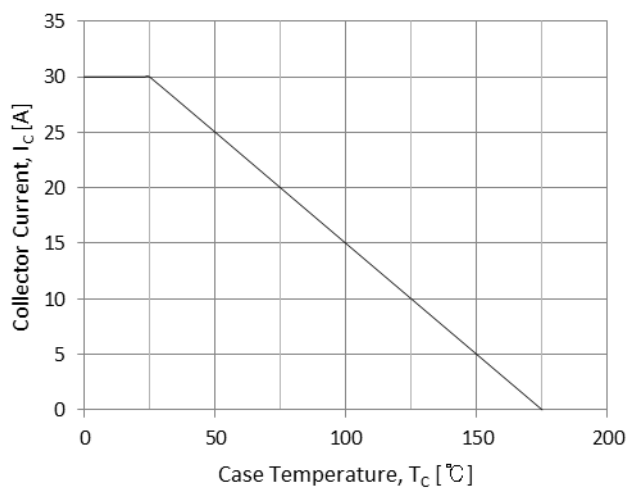


Fig.19 Case Temperature-Collector Current

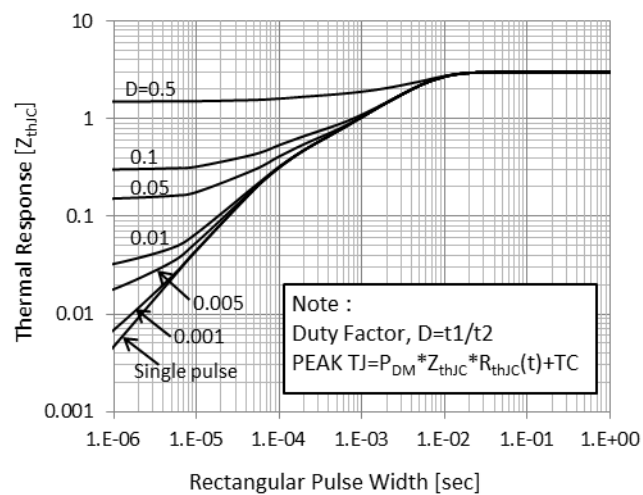


Fig.20 IGBT Transient Thermal Impedance

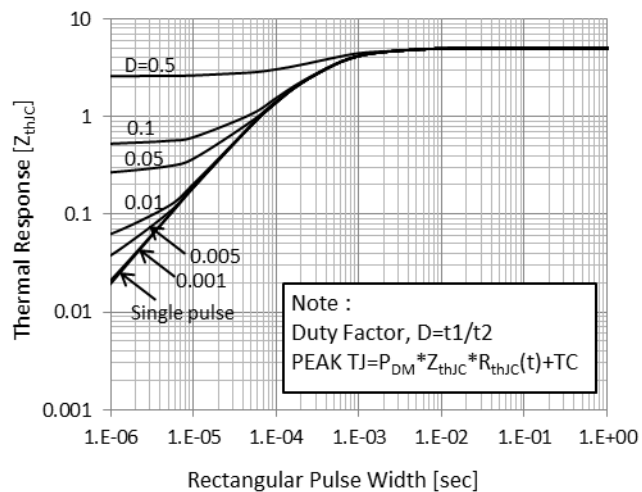
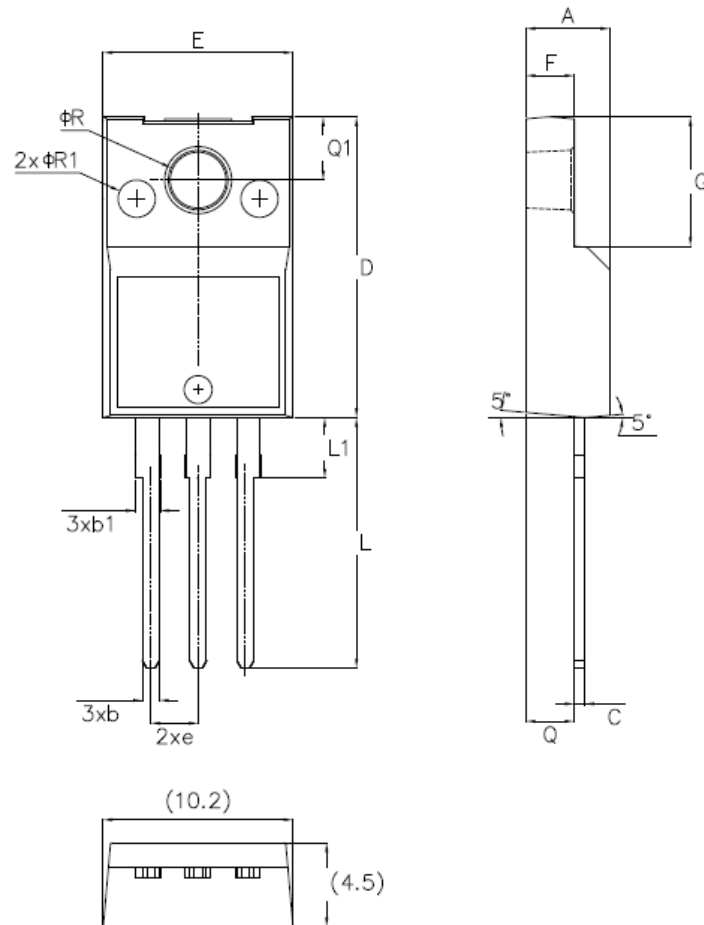


Fig.21 FRD Transient Thermal Impedance

Package outline dimension

TO-220F



Symbol	Dimension (mm)		
	Min	Nom	Max
A	4.3	—	4.8
b	0.5	—	1.0
b1	0.95	—	1.7
C	0.4	—	0.8
D	14.5	—	16.4
E	9.6	—	10.4
e	2.54 BSC		
F	2.5	—	3.1
G	6.2	—	7.2
L	12.2	—	14.2
L1	2.9	—	4.7
Q	2.3	—	2.9
Q1	2.4	—	3.5
ΦR	3.00	—	3.4
$\Phi R1$	2.0		

DISCLAIMER:

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